
Features

- EE Programmable 1,048,576 x 1-bit Serial Memory Designed to Store Configuration Programs for Field Programmable Gate Arrays (FPGAs)
- Very Low-power CMOS EEPROM Process
- In-System Programmable (ISP) via Two-Wire Bus
- Simple Interface to SRAM FPGAs
- Compatible with AT40K Devices
- Cascadable Read-back to Support Additional Configurations or Higher-density Arrays
- Programmable Reset Polarity
- Low-power Standby Mode
- High-reliability
 - Endurance: 5,10⁽⁴⁾ Read Cycles
- Data Retention: 10 Years
- No Single Event Latch-up below a LET Threshold of 80 MeV/mg/cm²
- Tested up to a Total Dose of 20 krad (Si) according to MIL STD 883 Method 1019
- Operating Range: 3.0V to 3.6V, -55°C to +125°C
- Available in 400 mils Wide 28 Pins DIL Flat Pack

Description

The AT17LV010-10DP is a FPGA Configuration EEPROM provides an easy-to-use, cost-effective configuration memory for Field Programmable Gate Arrays. It is packaged in the 28-pin 400 mils wide FP package. Configurator uses a simple serial-access procedure to configure one or more FPGA devices. The user can select the polarity of the reset function by programming four EEPROM bytes. The device also supports a write-protection mechanism within its programming mode.



Space FPGA Configuration EEPROM

**AT17LV010-
10DP**

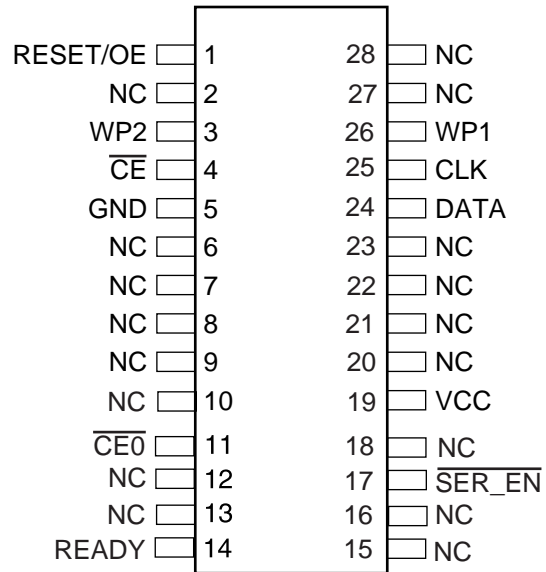
**Advance
Information**

Rev. 4265B-AERO-06/04



Pin Configuration

Figure 1. 28-pin Flat Pack



Pin Description

DATA	Tri-state DATA output for configuration. Open-collector bi-directional pin for programming.
CLK	Clock input. Used to increment the internal address and bit counter for reading and programming.
WP1	WRITE PROTECT (1). Used to protect portions of memory during programming. Disabled by default due to internal pull-down resistor. This input pin is not used during FPGA loading operations.
RESET/OE	Output Enable (active High) and RESET (active Low) when $\overline{\text{SER_EN}}$ is High. A Low level on $\overline{\text{RESET/OE}}$ resets both the address and bit counters. A High level (with $\overline{\text{CE}}$ Low) enables the data output driver. The logic polarity of this input is programmable as either $\overline{\text{RESET/OE}}$ or $\overline{\text{RESET/OE}}$. For most applications, RESET should be programmed active Low. This document describes the pin as $\overline{\text{RESET/OE}}$.
WP2	WRITE PROTECT (2). Used to protect portions of memory during programming. Disabled by default due to internal pull-down resistor. This input pin is not used during FPGA loading operations.
$\overline{\text{CE}}$	Chip Enable input (active Low). A Low level (with OE High) allows CLK to increment the address counter and enables the data output driver. A High level on $\overline{\text{CE}}$ disables both the address and bit counters and forces the device into a low-power standby mode. Note that this pin will <i>not</i> enable/disable the device in the Two-Wire Serial Programming mode ($\overline{\text{SER_EN}}$ Low).
GND	Ground pin. A 0.2 μF decoupling capacitor between V_{CC} and GND is recommended.
$\overline{\text{CEO}}$	Chip Enable Output (active Low). This output goes Low when the address counter has reached its maximum value. In a daisy chain of AT17LV010-10DP devices, the $\overline{\text{CEO}}$ pin of one device must be connected to the $\overline{\text{CE}}$ input of the next device in the chain. It will stay Low as long as $\overline{\text{CE}}$ is Low and OE is High. It will then follow CE until OE goes Low; thereafter, $\overline{\text{CEO}}$ will stay High until the entire EEPROM is read again.
A2	Device selection input, A2. This is used to enable (or select) the device during programming (i.e., when $\overline{\text{SER_EN}}$ is Low). A2 has an internal pull-down resistor.
READY	Open collector reset state indicator. Driven Low during power-up reset, released when power-up is complete. It is recommended to use a 4.7 k Ω pull-up resistor when this pin is used.
$\overline{\text{SER_EN}}$	Serial enable must be held High during FPGA loading operations. Bringing $\overline{\text{SER_EN}}$ Low enables the Two-Wire Serial Programming Mode. For non-ISP applications, $\overline{\text{SER_EN}}$ should be tied to V_{CC} .
V_{CC}	3.3V ($\pm 0.3\text{V}$).

FPGA Master Serial Mode Summary

The I/O and logic functions of any SRAM-based FPGA are established by a configuration program. The program is loaded either automatically upon power-up, or on command, depending on the state of the FPGA mode pins. In Master mode, the FPGA automatically loads the configuration program from an external memory. The AT17LV Serial Configuration EEPROM has been designed for compatibility with the Master Serial mode.

This document discusses the Atmel AT40KEL applications.

Control of Configuration

Most connections between the FPGA device and the AT17LV Serial EEPROM are simple and self-explanatory.

- The DATA output of the AT17LV010-10DP configurator drives DIN of the FPGA devices.
- The master FPGA CCLK output drives the CLK input of the AT17LV010-10DP configurator.
- The $\overline{\text{CEO}}$ output of any AT17LV010-10DP configurator drives the $\overline{\text{CE}}$ input of the next configurator in a cascaded chain of EEPROMs.
- $\overline{\text{SER_EN}}$ must be connected to V_{CC} (except during ISP).
- The READY pin is available as an open-collector indicator of the device's reset status; it is driven Low while the device is in its power-on reset cycle and released (tri-stated) when the cycle is complete.

Cascading Serial Configuration EEPROMs

For multiple FPGAs configured as a daisy-chain, or for FPGAs requiring larger configuration memories, cascaded configurators provide additional memory.

After the last bit from the first configurator is read, the clock signal to the configurator asserts its $\overline{\text{CEO}}$ output Low and disables its DATA line driver. The second configurator recognizes the Low level on its $\overline{\text{CE}}$ input and enables its DATA output.

After configuration is complete, the address counters of all cascaded configurators are reset if the $\overline{\text{RESET/OE}}$ on each configurator is driven to its active (Low) level.

If the address counters are not to be reset upon completion, then the $\overline{\text{RESET/OE}}$ input can be tied to its inactive (High) level.

Reset PAT17LV010-10DPolarity

The AT17LV010-10DP configurator allows the user to program the reset polarity as either $\overline{\text{RESET/OE}}$ or $\overline{\text{RESET/OE}}$. This feature is supported by industry-standard programmer algorithms.

Programming Mode

The programming mode is entered by bringing $\overline{\text{SER_EN}}$ Low. In this mode the chip can be programmed by the Two-Wire serial bus. The programming is done at V_{CC} supply only. Programming super voltages are generated inside the chip.

Standby Mode

The AT17LV010-10DP configurator enter a low-power standby mode whenever $\overline{\text{CE}}$ is asserted High. In this mode, the AT17LV010-10DP configurator consumes less than 100 μA of current at 3.3V. The output remains in a high-impedance state regardless of the state of the $\overline{\text{OE}}$ input.

Electrical Characteristics

Absolute Maximum Ratings*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on Any Pin with Respect to Ground	-0.1V to $V_{CC} + 0.5V$
Supply Voltage (V_{CC})	-0.5V to +7.0V
Maximum Soldering Temp. (10 sec. @ 1/16 in.).....	260°C
ESD ($R_{ZAP} = 1.5K$, $C_{ZAP} = 100$ pF).....	2000V

*NOTICE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those listed under operating conditions is not implied. Exposure to Absolute Maximum Rating conditions for extended periods of time may affect device reliability.

Operating Conditions

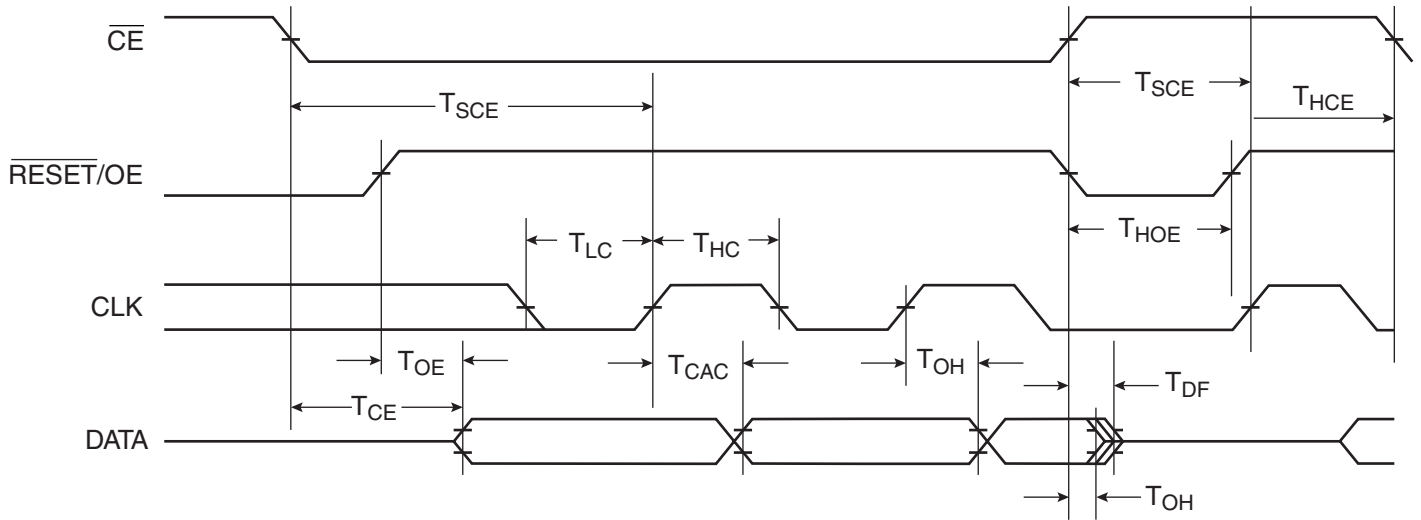
Symbol	Description	3.3V		Units	
		Min	Max		
V_{CC}	Military	-55 to +125°C	3.0	3.6	V

DC Characteristics

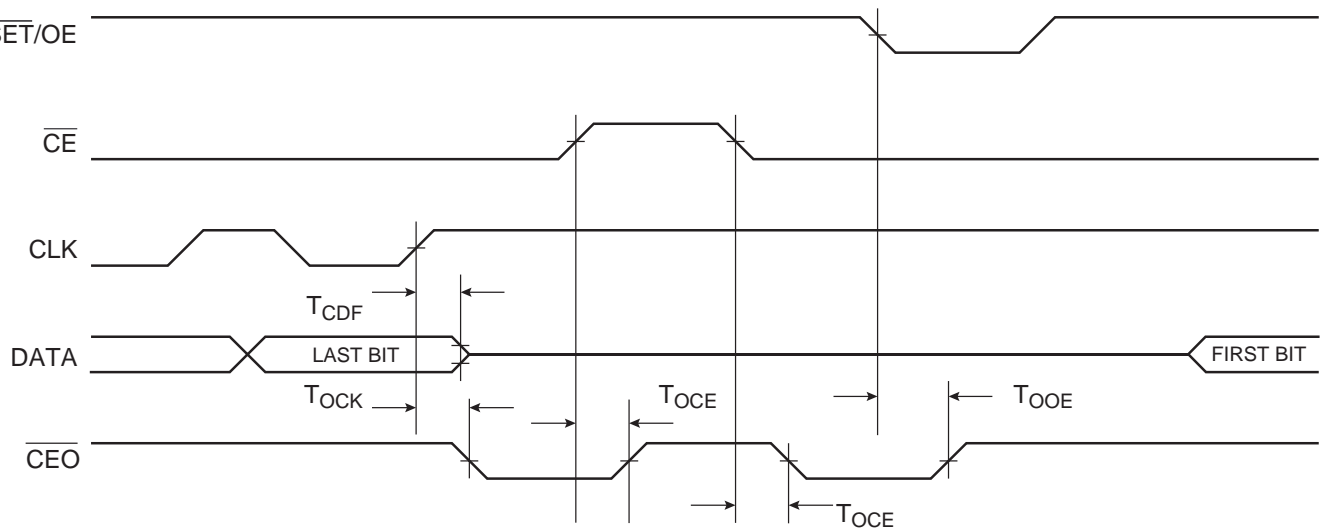
$$V_{CC} = 3.3V \pm 0.3V$$

Symbol	Description	AT17LV010-10DP		Units
		Min	Max	
V_{IH}	High-level Input Voltage	2.0	V_{CC}	V
V_{IL}	Low-level Input Voltage	0	0.8	V
V_{OH}	High-level Output Voltage ($I_{OH} = -2.5$ mA)	2.4		V
V_{OL}	Low-level Output Voltage ($I_{OL} = +3$ mA)		0.4	V
I_{CCA}	Supply Current, Active Mode		10	mA
I_L	Input or Output Leakage Current ($V_{IN} = V_{CC}$ or GND)	-10	10	μA
I_{CCS}	Supply Current, Standby Mode		200	μA

AC Characteristics



AC Characteristics when Cascading



AC Characteristics

$$V_{CC} = 3.3V \pm 0.3V$$

Symbol	Description	Military		Units
		Min	Max	
$T_{OE}^{(1)}$	OE to Data Delay		55	ns
$T_{CE}^{(1)}$	\overline{CE} to Data Delay		60	ns
$T_{CAC}^{(1)}$	CLK to Data Delay		60	ns
T_{OH}	Data Hold from \overline{CE} , OE, or CLK	0		ns
$T_{DF}^{(2)}$	\overline{CE} or OE to Data Float Delay		50	ns
T_{LC}	CLK Low Time	25		ns
T_{HC}	CLK High Time	25		ns
T_{SCE}	\overline{CE} Setup Time to CLK (to guarantee proper counting)	35		ns
T_{HCE}	\overline{CE} Hold Time from CLK (to guarantee proper counting)	0		ns
T_{HOE}	OE High Time (guarantees counter is reset)	25		ns
F_{MAX}	Maximum Clock Frequency		10	MHz

- Notes:
1. AC test lead = 50 pF.
 2. Float delays are measured with 5 pF AC loads. Transition is measured ± 200 mV from steady-state active levels.

AC Characteristics when Cascading

$$V_{CC} = 3.3V \pm 0.3V$$

Symbol	Description	Military		Units
		Min	Max	
$T_{CDF}^{(2)}$	CLK to Data Float Delay		50	ns
$T_{OCK}^{(1)}$	CLK to \overline{CEO} Delay		55	ns
$T_{OCE}^{(1)}$	\overline{CE} to \overline{CEO} Delay		40	ns
$T_{OOE}^{(1)}$	$\overline{RESET/OE}$ to \overline{CEO} Delay		40	ns
F_{MAX}	Maximum Clock Frequency		10	MHz

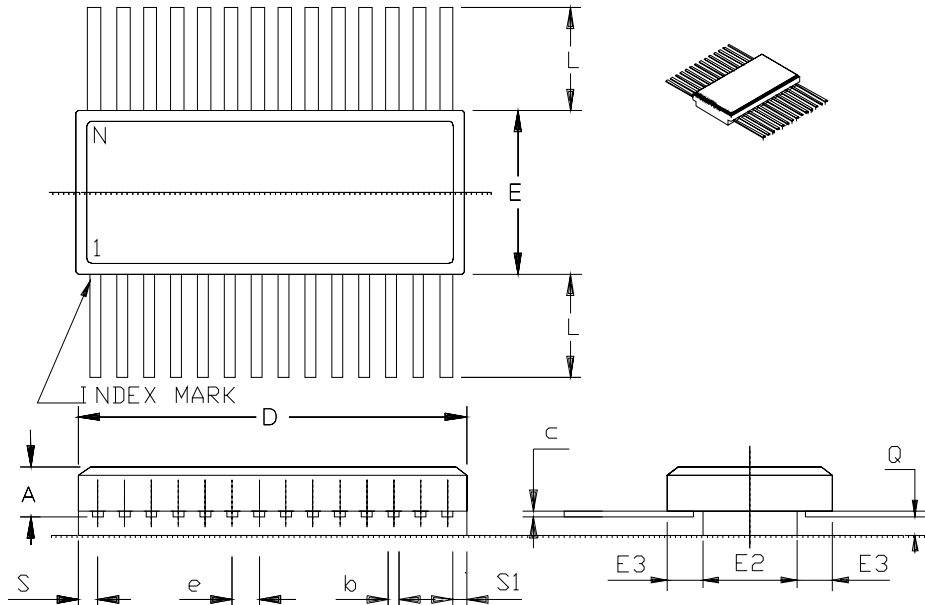
- Notes:
1. AC test lead = 50 pF.
 2. Float delays are measured with 5 pF AC loads. Transition is measured ± 200 mV from steady-state active levels.

Ordering Information

Memory Size	Ordering Code	Package	Operation Range
1 Mbit	AT17LV010-10DP-E	28-pin Flat Pack	Engineering Samples
1 Mbit	AT17LV010-10DP-M	28-pin Flat Pack	Standard Mil. Temperature
1 Mbit	AT17LV010-10DP-MQ	28-pin Flat Pack	QML Q
1 Mbit	AT17LV010-10DP-SV	28-pin Flat Pack	QML V

Packaging Information

DP (FP28.4)



	Min	MM	Max	Min	INCH	Max
A	2.29		3.30	.090		.130
b	0.38		0.48	.015		.019
c	0.08		0.15	.003		.006
D	---		18.80	---		.740
E	9.65		10.67	.380		.420
E2	4.57		---	.180		---
E3	0.76		---	.030		---
e	1.27	BSC		.050	BSC	
L	6.35		9.40	.250		.370
Q	0.66		---	.026		---
S	---		1.30	---		.051
S1	0.00		---	.000		---
N		28			28	



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